

SID

Factory: Rot am See

Article:

ML6

Provided:

Customer:

Date:

03.04.2026

WÜRTH  
ELEKTRONIK  
MORE THAN  
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-035my 330x490mm	50200242	35	VS	1	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	169		2	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		3	
		70	L2		
C-STD-FR4-ML-0.711mm-070+070-TG150-H...	50203136	710		4	A01
		70	L3		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	183		5	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		6	B00
		70	L4		
C-STD-FR4-ML-0.711mm-070+070-TG150-H...	50203136	710		7	A02
		70	L5		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	169		8	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		9	
A-RS Kupferfolie-035my 330x490mm	50200242	35	RS	10	

Thickness after Pressing

B00:

2290 µm

Tol+:

240 µm

Tol-:

240 µm

Dmax:

2530 µm

Dmin:

2050 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

2400 µm

Tol+:

240 µm

Tol-:

240 µm

Dmax:

2640 µm

Dmin:

2160 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

2291 µm

Version 1.2.20.35

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